# **ABSOLUTE MAXIMUM RATINGS**

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

# DC ELECTRICAL CHARACTERISTICS

 $(V_{CC} = +2.97 V \text{ to } +3.63 V, 150\Omega \text{ load between OUT+ and OUT-}, T_j = -40 ^{\circ}\text{C} \text{ to } +100 ^{\circ}\text{C}.$  Typical values are at  $V_{CC} = +3.3 V$  and  $T_{A} = +25 ^{\circ}\text{C}$ , unless otherwise noted.)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Supply Current	Icc			20	26	mA
Input Bias Voltage	V <sub>IN</sub>	$I_{IN} = 1\mu A$		0.83	1.0	V
Transimpedance Linear Range		0.95 < linearity < 1.05	4			µA <sub>P-P</sub>
Small-Signal Transimpedance	Z <sub>21</sub>	I <sub>IN</sub> < 2µA <sub>P-P</sub>	15.7	18.3	20.9	kΩ
Output Common-Mode Voltage		AC-coupled output		V <sub>CC</sub> - 0.125		V
Differential Output Offset	ΔV <sub>OUT</sub>	$I_{IN} = 1.3 \text{mA}$		±2		mV
Output Impedance	Z <sub>OUT</sub>	Single ended	60	75	90	Ω
Maximum Output Voltage	Vout(max)	$I_{IN} = 2mA_{P-P}$	150	240	400	mV <sub>P-P</sub>
Filter Resistor	D	$I_{IN} = 4\mu A$	15	20	25	kΩ
Filler Resistor	RFILT	$I_{IN} = 1.3 \text{mA}$	300	500	700	Ω
Offset-Correction Disable Threshold		Voltage applied at FILT		0.4		V
Input Resistance		FILT = 0V		400		Ω
Nominal MON Current Gain	GMON	I <sub>MON</sub> / I <sub>IN</sub> (I <sub>IN</sub> = 1mA, 3.3V, +25°C)	0.8	1	1.2	A/A
MON Output Voltage Range	V <sub>MON</sub>		0		2.2	V
		1μA ≤ I <sub>IN</sub> < 2μA	-2.5		+2.5	
MON Accuracy (Note 1)		2μA ≤ I <sub>IN</sub> < 5μA	-2		+2	dB
		5μA ≤ I <sub>IN</sub> < 1mA	-1.5	•	+1.5	

Note 1: Accuracy is defined as  $10_{log}(I_{MON} / I_{lN})$ .



# **AC ELECTRICAL CHARACTERISTICS**

 $(V_{CC} = +2.97 V \text{ to } +3.63 V, 150 \Omega \text{ load between OUT+} \text{ and OUT-}, C_{IN} = 0.5 pF \text{ total}, C_{FILT} = 400 pF, C_{VCC2} = 1 nF, T_j = -40 ^{\circ} C \text{ to } +100 ^{\circ} C, T_A = -40 ^{\circ} C \text{ to } +85 ^{\circ} C.$  Typical values are at  $V_{CC} = +3.3 V$  and  $T_A = +25 ^{\circ} C$ , unless otherwise noted. AC characteristics are guaranteed by design and characterization.)

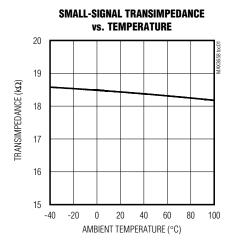
PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Bandwidth	BW	(Note 2)	435	580		MHz
Input-Referred Noise	in	BW = 467MHz		45	55	nA <sub>RMS</sub>
Noise Density		BW = 467MHz		2.1		pA/√Hz
Low-Frequency Cutoff		$I_{IN} = 1\mu A$			30	kHz
Deterministic Jitter (Note 3)	DJ	2μΑ <sub>P-P</sub> ≤ I <sub>IN</sub> < 10μΑ <sub>P-P</sub>			150	202.5
Deterministic sitter (Note 3)	DJ	10μAp-p ≤ I <sub>IN</sub> < 2mAp-p			260	psp-p
Orational Organism d		1.0A/W photodiode at 622 Mbps		+1		dBm
Optical Overload	PIN(MAX)	1.0A/W photodiode at 155 Mbps		-7.2		иын
Optical Sensitivity	PIN(MIN)	0.9A/W photodiode		-33		dBm

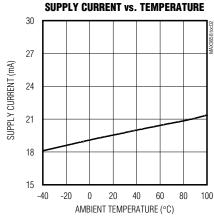
Note 2: -3dB bandwidth is measured relative to the gain at 10MHz.

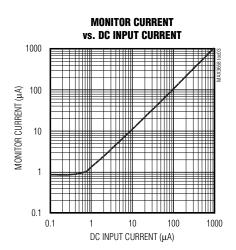
**Note 3:** Measured using a pattern equivalent to  $2^{23}$  - 1 PRBS with 72 CIDs at 622Mbps.

# Typical Operating Characteristics

( $V_{CC}$  = +3.3V,  $C_{IN}$  = 0.5pF,  $T_A$  = +25°C, unless otherwise noted.)

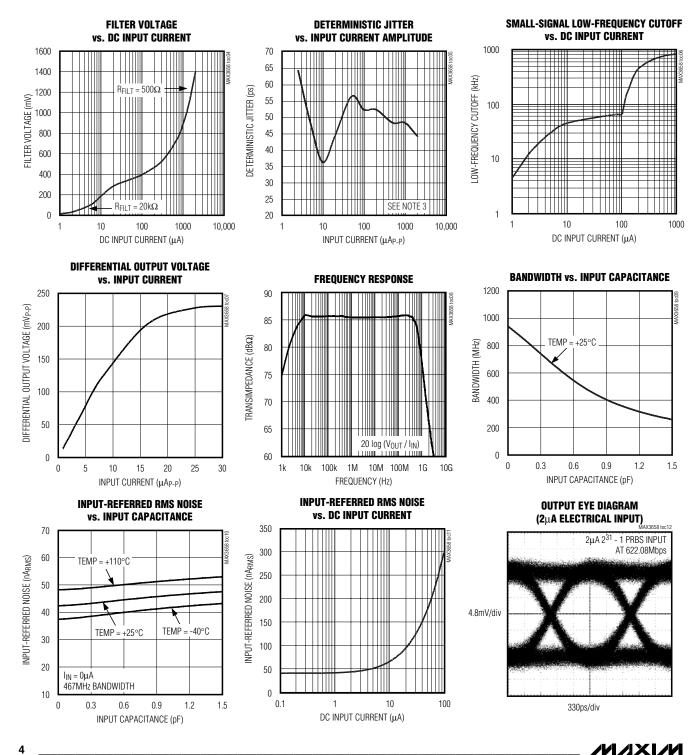






# Typical Operating Characteristics (continued)

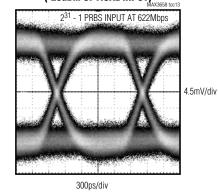
( $V_{CC} = +3.3V$ ,  $C_{IN} = 0.5pF$ ,  $T_A = +25^{\circ}C$ , unless otherwise noted.)



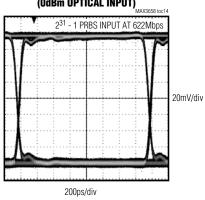
# Typical Operating Characteristics (continued)

(V<sub>CC</sub> = +3.3V, C<sub>IN</sub> = 0.5pF, T<sub>A</sub> = +25°C, unless otherwise noted.)

## OUTPUT EYE DIAGRAM (-28dBm OPTICAL INPUT)



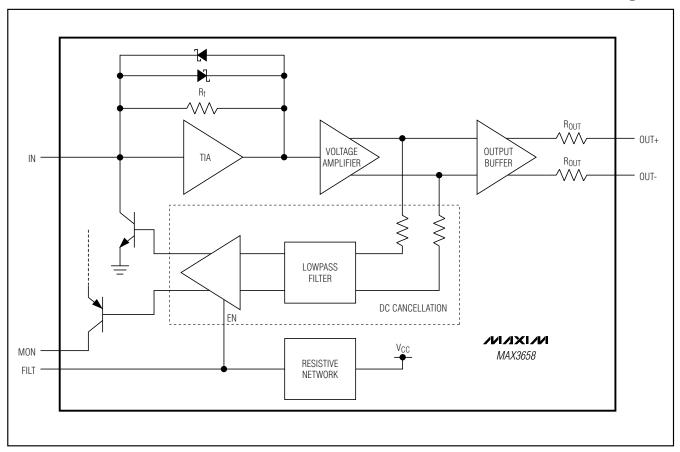
#### OUTPUT EYE DIAGRAM (OdBm OPTICAL INPUT)



# Pin Description

PIN	NAME	FUNCTION
1	Vcc	+3.3V Supply Voltage
2	IN	Signal Input. Connect to photodiode anode.
3	FILT	Optional Filter Connection. Use to bias the photodiode cathode. An internal on-chip resistive network is connected between this pin and V <sub>CC</sub> ; an external decoupling capacitor connected to this pin forms a filter (see the <i>Design Procedure</i> section). Leave this pin open if a filter is not required.
4	MON	Optional Photocurrent Monitor. This is a current output. Connect a resistor between MON and ground to monitor the average photocurrent. Leave this pin open if a monitor is not required.
5, 8	GND	Circuit Ground
6	OUT+	Positive 75Ω Data Output. Increasing input current causes OUT+ to increase.
7	OUT-	Negative 75 $\Omega$ Data Output. Increasing input current causes OUT- to decrease.

# Functional Diagram



# **Detailed Description**

The MAX3658 transimpedance amplifier is designed for 622Mbps fiber optic applications. The MAX3658 is comprised of a transimpedance amplifier, a voltage amplifier, an output buffer, a DC cancellation circuit, and a photocurrent monitor.

## **Transimpedance Amplifier**

The signal current at the input flows into the summing node of a high-gain amplifier. Shunt feedback through resistor RF converts this current into a voltage. Schottky diodes clamp the output signal for large input currents (Figure 1).

# **Voltage Amplifier**

The voltage amplifier provides additional gain and converts the transimpedance amplifier single-ended output into a differential signal.

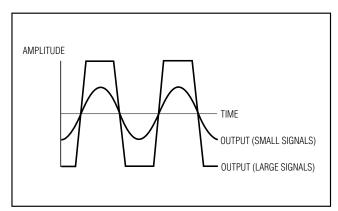


Figure 1. MAX3658 Limited Output

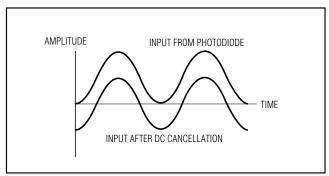


Figure 2. DC Cancellation Effect on Input

## **Output Buffer**

The output buffer is designed to drive a  $150\Omega$  differential load between OUT+ and OUT-. For optimum supply noise rejection, the MAX3658 should be terminated with a differential load. The MAX3658 single-ended outputs do not drive a DC-coupled grounded load. The outputs should be AC-coupled or terminated to V<sub>CC</sub>. If a single-ended output is required, both the used and the unused outputs should be terminated in a similar manner (see the *Interface Schematics* section).

### **DC Cancellation Circuit**

The DC cancellation circuit uses low-frequency feed-back to remove the DC component of the input signal (Figure 2). This feature centers the input signal within the transimpedance amplifier's linear range, thereby reducing pulse-width distortion.

The DC cancellation circuit is internally compensated and does not require external capacitors. This circuit minimizes pulse-width distortion for data sequences that exhibit a 50% mark density. A mark density significantly different from 50% causes the MAX3658 to generate pulse-width distortion. Grounding the FILT pin disables the DC cancellation circuit. For normal operation, the DC cancellation circuit must be enabled.

The DC cancellation current is drawn from the input and creates noise. For low-level signals with little or no DC component, the added noise is insignificant. However, amplifier noise increases for signals with significant DC component (see the *Typical Operating Characteristics*).

#### **Photocurrent Monitor**

The MAX3658 includes an average photocurrent monitor. The current sourced from MON to ground is approximately equal to the DC current at IN.

# \_Design Procedure

#### **Select Photodiode**

Noise performance and bandwidth are adversely affected by capacitance on the TIA input node. Select a low-capacitance photodiode to minimize the total input capacitance on this pin. The MAX3658 is optimized for 0.5pF of capacitance on the input. Assembling the MAX3658 in die form using chip and wire technology provides the lowest capacitance input and the best possible performance.

### Select CFILT

Supply voltage noise at the cathode of the photodiode produces a current  $i = C_{PD}$  dv/dt, which reduces the receiver sensitivity ( $C_{PD}$  is the photodiode capacitance). The filter resistor of the MAX3658 combined with an external capacitor, can be used to reduce the effect of supply noise on performance (see the *Typical Operating Circuit*). Current generated by supply noise voltage is divided between  $C_{FILT}$  and  $C_{PD}$ . To obtain a good optical sensitivity select  $C_{FILT} \approx 400 pF$ .

## **Select Supply Filter**

Sensitive optical receivers require wide-band power-supply decoupling. Power-supply bypassing should provide low impedance between V<sub>CC</sub> and ground for frequencies between 10kHz and 700MHz. Isolate the MAX3658 from noise sources with LC supply filters and shielding. Place a supply filter (C<sub>VCC2</sub>) as close to the MAX3658 as possible.

#### **Select Rmon**

If photocurrent monitoring is desired, connect a resistor between MON and ground to monitor the average photocurrent. Select R<sub>MON</sub> as large as possible:

$$R_{MON} = \frac{2.2V}{I_{MONMAX}}$$

where I<sub>MONMAX</sub> is the largest average input current observed. An ammeter can also monitor the current out of the MON pin.

#### Select Coupling Capacitors

A receiver built with the MAX3658 will have a bandpass frequency response. The low-frequency cutoff due to the coupling capacitors and load resistors is:

$$LFC_{TERM} = \frac{1}{2\pi \times R_{LOAD} \times C_{COUPLE}}$$

Select C<sub>COUPLE</sub> so the low-frequency cutoff due to the load resistors and coupling capacitors is much lower than the low-frequency cutoff of the MAX3658. The coupling capacitor should be 0.1µF or larger for SONET data. For lowest jitter, 1.0µF is recommended. Refer to application note HFAN-01.1: *Choosing AC-Coupling Capacitors* for a more detailed discussion on choosing AC-coupling capacitors.

## Select Output Filter

Input sensitivity is improved by adding a filter between TIA and the quantizer/limiting amplifier, with 0.5pF input capacitance. Typical bandwidth of the MAX3658 is 580MHz; the highest expected bandwidth is 730MHz.

## **Layout Considerations**

Figure 3 shows suggested layouts for 4- and 5-pin TO headers.

#### Wire Bonding

For high-current density and reliable operation, the MAX3658 uses gold metalization. For best results, use gold-wire ball-bonding techniques. Use caution when wedge bonding. Die-size is 52 mils x 29 mils, (1.32mm x 0.736mm) and die thickness is 15 mils (380µm). The bond-pad passivation opening is 75µm and bond-pad metal thickness is 5µm. Refer to Maxim application note HFAN-08.0.1: *Understanding Bonding Coordinates and Physical Die Size* for additional information on bond-pad coordinates.

# Applications Information Optical Power Relations

Many of the MAX3658 specifications relate to the input signal amplitude. When working with optical receivers, the input is sometimes expressed in terms of average optical power and extinction ratio. Figure 4 and Table 1 show relations that are helpful for converting optical power to input signal when designing with the MAX3658.

#### **Optical Sensitivity Calculation**

The input-referred RMS noise current  $(i_n)$  of the MAX3658 generally determines the receiver sensitivity. To obtain a system bit-error rate (BER) of 1E-10, the signal-to-noise ratio must always exceed 12.7. The input sensitivity, expressed in average power, can be estimated as:

$$SENSITIVITY = 10log \left( \frac{12.7 \times i_{n} \times (r_{e} + 1)}{2 \times \rho \times (r_{e} - 1)} \times 1000 \right) dBm$$

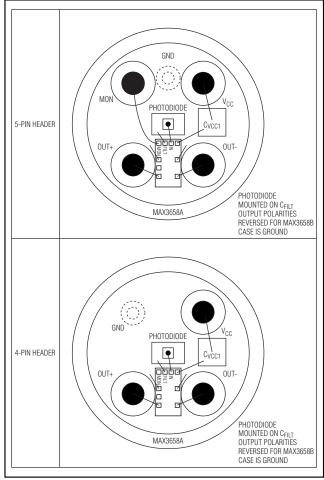


Figure 3. Suggested TO Header Layouts

# **Table 1. Optical Power Relations\***

PARAMETER	SYMBOL	RELATION
Average Power	P <sub>AVG</sub>	$P_{AVG} = \frac{P0 + P1}{2}$
Extinction Ratio	r <sub>e</sub>	$r_e = \frac{P1}{P0}$
Optical Power of a 1	P1	$P1 = 2P_{AVG} \frac{r_e}{r_e + 1}$
Optical Power of a 0	P0	$PO = \frac{2P_{AVG}}{r_e + 1}$
Optical Modulation Amplitude	Pin	$P_{N} = P1 - P0$ = $2P_{AVG} \frac{r_{e} - 1}{r_{e} + 1}$

<sup>\*</sup>Assuming a 50% average mark density.

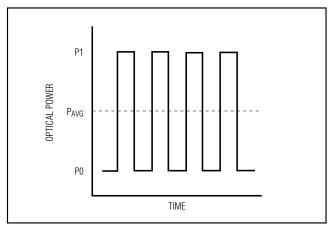


Figure 4. Optical Power Relations

where  $\rho$  is the photodiode responsivity in A/W and  $i_{n}$  is the RMS noise current in amps. For example, with photodiode responsivity of 0.9A/W, an extinction ratio of 10 and 45nA input-referred noise, the sensitivity of the MAX3658 is:

SENSITIVITY = 
$$10\log\left(\frac{12.7 \times 45 \text{nA} \times 11}{2 \times 0.9 \text{A/W} \times 9} \times 1000\right) \text{dBm}$$
  
=  $-34 \text{dBm}$ 

Actual results may vary depending on supply noise, output filter, limiting amplifier sensitivity, and other factors (refer to application note HFAN-03.0.0: *Accurately Estimating Optical Receiver Sensitivity*).

Maxim obtains -33dBm typ sensitivity combined with the MAX3748.

#### **Input Optical Overload**

Overload is the largest input that the MAX3658 accepts while meeting the pulse-width distortion specification. Optical overload can be estimated in terms of average power with the following equation:

OVERLOAD = 
$$10\log\left(\frac{2mA}{2 \times \rho} \times 1000\right) dBm$$

For example, if photodiode responsivity is 1.0A/W, the input overload is 0dBm.

## **Optical Linear Range**

The MAX3658 has high gain, which limits the output for large input signals. The MAX3658 operates in a linear range for inputs not exceeding:

LINEAR RANGE = 
$$10log \left( \frac{4\mu A \times (r_e + 1)}{2 \times \rho \times (r_e - 1)} \times 1000 \right) dBm$$

For example, with photodiode responsivity of 0.9A/W and an extinction ratio of 10, the linear range is:

LINEARRANGE = 
$$10\log\left(\frac{4\mu A \times 11}{2 \times 0.9 \times 9} \times 1000\right) dBm$$
  
=  $-25dBm$ 

# Interface Schematics

## **Equivalent Output Interface**

The MAX3658 has a differential output structure with  $75\Omega$  termination (150 $\Omega$  differential). Figure 5 is a simplified diagram of the output interface. Common test equipment is designed with a  $50\Omega$  single-ended termination (100 $\Omega$  differential). Figures 6a and 6b show alternate interface schemes for the MAX3658.

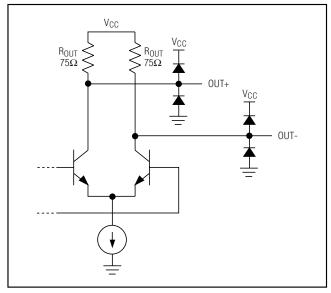


Figure 5. Equivalent Output Interface

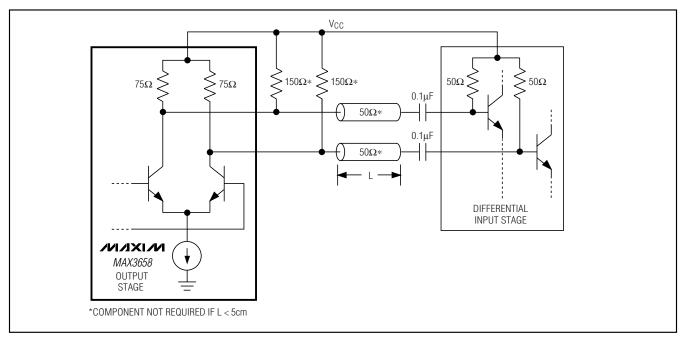


Figure 6a.  $50\Omega$  AC-Coupled Interface

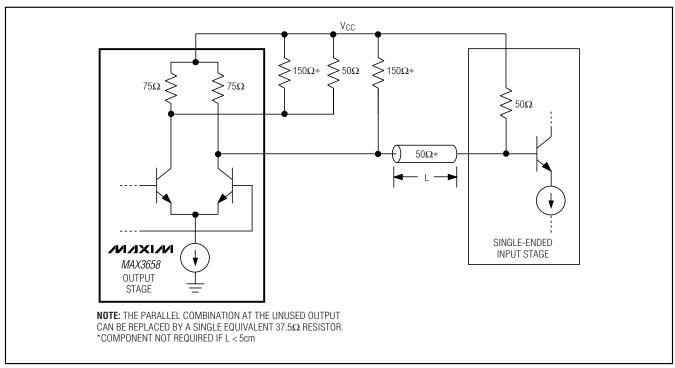


Figure 6b.  $50\Omega$  DC-Coupled Single-Ended Output Interface

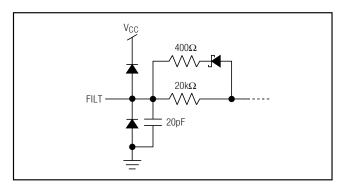


Figure 7. FILT Interface

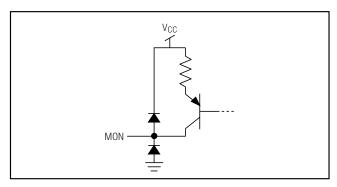


Figure 8. MON Interface

# **Pad Coordinates**

Table 2 gives center pad coordinates for the MAX3658 bond pads. Refer to application note HFAN-08.0.1: *Understanding Bonding Coordinates and Physical Die Size* for more information on bond-pad coordinates.

## **Table 2. Bond-Pad Information**

	NA	ME	COORDIN	COORDINATES (µm)		
PAD	MAX3658A	MAX3658B	Х	Y		
BP1	MON	MON	16.6	818.6		
BP2	GND	GND	18.0	543.4		
BP3	N.C.	N.C.	18.0	425.8		
BP4	OUT+	OUT-	16.6	39.4		
BP5	OUT-	OUT+	445.0	39.4		
BP6	N.C.	N.C.	456.2	155.6		
BP7	GND	GND	455.0	565.8		
BP8	Vcc	Vcc	455.0	818.6		
BP9	IN	IN	254.6	818.6		
BP10	FILT	FILT	135.6	818.6		

# **Pin Configuration**

# TOP VIEW GND OUT- OUT+ GND 8 7 6 5 MAX3658 AGP\*\* VCC IN FILT MON TDFN\* (3mm x 3mm) \*THE EXPOSED PAD MUST BE CONNECTED TO CIRCUIT BOARD GROUND FOR PROPER THERMAL AND ELECTRICAL PERFORMANCE. \*\*AGP = DEVICE TOPMARK.

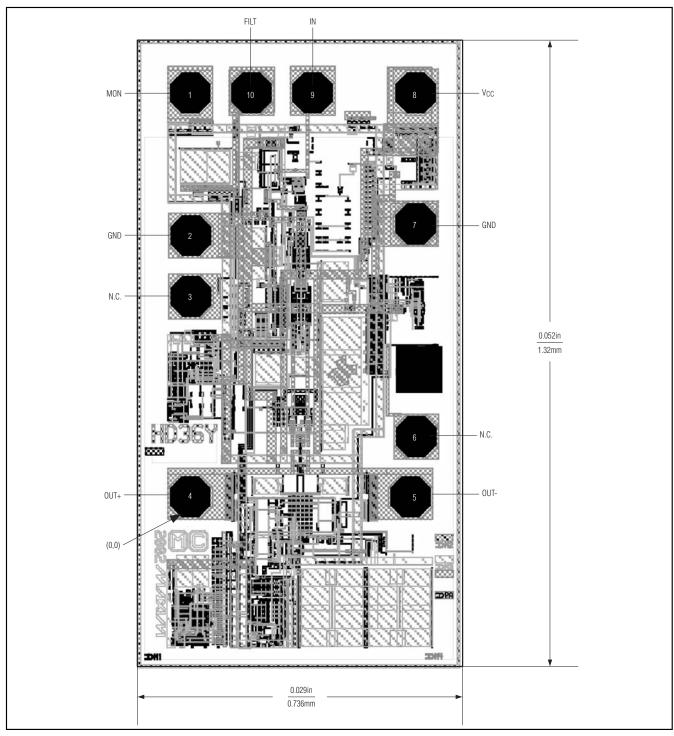
# **Chip Information**

TRANSISTOR COUNT: 833

PROCESS: GST-4

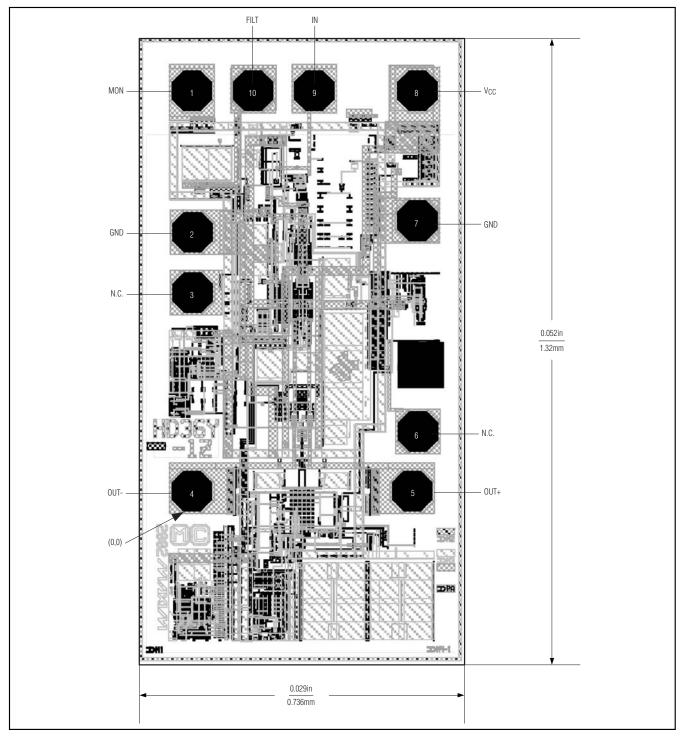
Chip Topographies

**Topography for MAX3658A** 



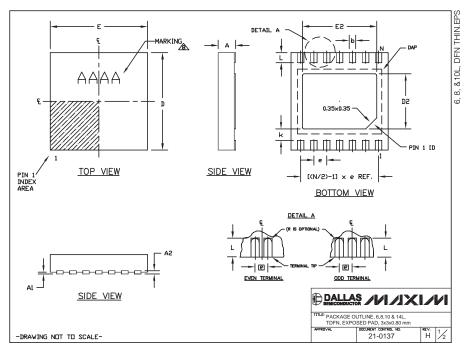
Chip Topographies (continued)

**Topography for MAX3658B** 



# **Package Information**

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information, go to <a href="https://www.maxim-ic.com/packages">www.maxim-ic.com/packages</a>.)



COWWON	DIMEN	SIONS		PACKAGE V	ARIAT	TIONS					
SYMBOL	MIN.	MAX.		PKG. CODE	N	D2	E2	е	JEDEC SPEC	b	[(N/2)-1] x e
Α	0.70	0.80		T633-1	6	1.50±0.10	2.30±0.10	0.95 BSC	MO229 / WEEA	0.40±0.05	1.90 REF
D	2.90	3.10		T633-2	6	1.50±0.10	2.30±0.10	0.95 BSC	MO229 / WEEA	0.40±0.05	1.90 REF
E	2.90	3.10		T833-1	8	1.50±0.10	2.30±0.10	0.65 BSC	MO229 / WEEC	0.30±0.05	1.95 REF
A1	0.00	0.05		T833-2	8	1.50±0.10	2.30±0.10	0.65 BSC	MO229 / WEEC	0.30±0.05	1.95 REF
L	0.20	0.40		T833-3	8	1.50±0.10	2.30±0.10	0.65 BSC	MO229 / WEEC	0.30±0.05	1.95 REF
k	0.25	MIN.		T1033-1	10	1.50±0.10	2.30±0.10	0.50 BSC	MO229 / WEED-3	0.25±0.05	2.00 REF
A2	0.20	REF.		T1033-2	10	1.50±0.10	2.30±0.10	0.50 BSC	MO229 / WEED-3	0.25±0.05	2.00 REF
				T1433-1	14	1.70±0.10	2.30±0.10	0.40 BSC		0.20±0.05	2.40 REF
				T1433-2	14	1.70±0.10	2.30±0.10	0.40 BSC		0.20±0.05	2.40 REF
2. COPL 3. WARP 4. PACK 5. DRAW 6. "N" I 7. NUME	ANARITY AGE SH AGE LE ING CO S THE BER OF	' SHALL IALL NO' NGTH/PA NFORMS TOTAL N LEADS	NOT EXC T EXCEE ACKAGE OF TO JED IUMBER OF SHOWN OF	. ANGLES IN CEED 0.08 m O 0.10 mm. WIDTH ARE CEC MO229, E OF LEADS. ARE FOR REF RIENTATION F	m. DNSID XCEP EREN	ERED AS S T DIMENSIO CE ONLY.	NS "D2" AN		C(S). ID T1433-1 & T	1433–2.	

4 \_\_\_\_\_\_*NIXIN* 

**Revision History** 

Rev 0; 10/03: Initial data sheet release.

Rev 1; 5/04: Added line to EC table regarding Optical Overload at 155MHz (page 3).

Rev 2; 11/05: Changed TO layout in Figure 3 (page 8).

Rev 3; 2/07: Added lead-free package to Ordering Information table (page 1).

Maxim cannot assume responsibility for use of any circuitry other than circuitry entirely embodied in a Maxim product. No circuit patent licenses are implied. Maxim reserves the right to change the circuitry and specifications without notice at any time.

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